

**PRODUCT DESCRIPTION**

C400™ provides the following product characteristics:

Technology	Cored solder wire
Product Benefits	• Halide free • No clean • Clear residue • Good wetting • Fast soldering • Heat stable • Mild odor • Pb-free and SnPb alloys available
IPC/J-STD-004 Classification	ROL0
Application	Soldering - Cored wire
Surface Finishes	Copper, Brass and Nickel

C400™ cored solder wire has been specially formulated to complement no clean wave and reflow soldering processes. C400™ wires provide fast soldering on copper, brass, and solder coated materials.

TYPICAL PROPERTIES**Solder Cored Wire**

Alloys - Tin/lead	• SN63 • SN60 • SN62
Alloys - Lead Free	• 97SC (SAC305) • 96SC (SAC387) • 99C (SnCu) • 95A (SnSb) • 96S (SnAg)
Acid Value	205 to 220 mg KOH/g
Halide content	Zero
Flux Content (%)	2.2

ALLOYS:

The alloys used in C400™ cored solder wires conform to the purity requirements of the common national and international standards.

FLUX:

C400™ solid flux is based on modified rosin and carefully selected activators. In practice they exhibit a mild rosin odor and leave a small quantity of clear residue.

DIRECTIONS FOR USE

Soldering with C400™ does not require any special methods or deviation from standard hand soldering practices.

Soldering Iron:

- Good results can be obtained using a range of tip temperatures. However, the optimum tip temperature and heat capacity required for a hand-soldering process is a function of both soldering iron design and the nature of the task.
- Care should be exercised to avoid unnecessarily high tip temperatures for extensive periods of time.
- A high tip temperature may increase any tendency to flux spitting and it may produce some residue darkening.
- The tip of the soldering iron should be properly tinned. Severely contaminated soldering iron tips should be cleaned with Multicore® Tip Tinner/Cleaner.
- Wipe the tip on a clean, damp sponge before re-tinning with C400™ wire.

Soldering Process:

1. Apply the soldering iron tip to the work surface. The iron tip should contact both the base material and the lead at the same time to heat both surfaces properly. It should take no more than a fraction of a second to heat both surfaces adequately.
2. Apply C400™ flux cored wire to a part of the joint surface away from the soldering iron and allow to form a joint fillet. This will be virtually instantaneous. Do not apply excessive solder to the joint as this will not improve joint integrity and it will leave excess flux residues on the surface.
3. Remove solder from the work piece and then remove the iron tip.
4. The total process will be very rapid, depending upon thermal mass, tip temperature, tip configuration and the solderability of the surfaces to be joined.
5. The resin and flux systems are designed to leave relatively low residues and to minimize residual activity. This is achieved by ensuring some decomposition and volatilization takes place during the soldering process

Cleaning:

C400™ flux cored solder wire has been formulated to leave amber flux residues and resist spitting and fuming. In most industrial and consumer electronics applications, cleaning will not be required. The product may, therefore, be used to complement a no-clean wave soldering or reflow process or to allow repairs to cleaned boards without the need for a second cleaning process. In high-reliability applications, the residues should be removed.

Should cleaning be required, this is best achieved using SC-01™ cleaner.

RELIABILITY PROPERTIES

J-STD-004	Solder spread mm ²	210
	Corrosion Test	Pass
SIR (without cleaning)	IPC-SF-818 Class 3	Pass
	Bellcore	Pass
	TR-NWT-000078	
Electromigration (without cleaning)	Bellcore	Pass
	TR-NWT-000078	
Classification	EN29454-1	1.1.3
	IPC-SF-818	LR3CN

PACKAGING

C400™ is available in various diameters, flux percentages, and reel sizes.

DATA RANGES

The data contained herein may be reported as a typical value and/or a range. Values are based on actual test data and are verified on a periodic basis.

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Not for Product Specifications

The technical information contained herein is intended for reference only. Please contact Henkel Corporation Technical Service for assistance and recommendations on specifications for this product.

Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\mu\text{m} / 25.4 = \text{mil}$
 $\text{N} \times 0.225 = \text{lb}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{N/mm}^2 \times 145 = \text{psi}$
 $\text{MPa} \times 145 = \text{psi}$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Reference 0.0